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- 2-V to 5.5-V V<sub>CC</sub> Operation
- Max t<sub>pd</sub> of 6 ns at 5 V
- Typical V<sub>OLP</sub> (Output Ground Bounce)
  <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
  >2.3 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

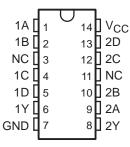
#### description/ordering information

These dual 4-input positive-NAND gates are designed for 2-V to 5.5-V  $\rm V_{CC}$  operation.

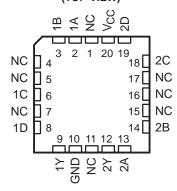
The 'LV20A devices perform the Boolean function  $Y = \overline{A} \bullet \overline{B} \bullet \overline{C} \bullet \overline{D}$  or  $Y = \overline{A} + \overline{B} + \overline{C} + \overline{D}$  in positive logic.

These devices are fully specified for partial-power-down applications using  $I_{\rm off}$ . The  $I_{\rm off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

#### SN54LV20A . . . J OR W PACKAGE SN74LV20A . . . D, DB, DGV, NS, OR PW PACKAGE (TOP VIEW)



# SN54LV20A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

#### **ORDERING INFORMATION**

TA	PACKA	GEŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	0010 D	Tube of 50	SN74LV20AD	11/004	
	SOIC - D	Reel of 2500	SN74LV20ADR	LV20A	
	SOP – NS	Reel of 2000	SN74LV20ANSR	74LV20A	
4000 to 0500	SSOP – DB	Reel of 2000	SN74LV20ADBR	LV20A	
-40°C to 85°C		Tube of 90	SN74LV20APW		
	TSSOP - PW	Reel of 2000	SN74LV20APWR	LV20A	
		Reel of 250	SN74LV20APWT		
	TVSOP - DGV	Reel of 2000	SN74LV20ADGVR	LV20A	
	CDIP – J	Tube of 25	SNJ54LV20AJ	SNJ54LV20AJ	
–55°C to 125°C	CFP – W	Tube of 150	SNJ54LV20AW	SNJ54LV20AW	
	LCCC – FK	Tube of 55	SNJ54LV20AFK	SNJ54LV20AFK	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



# FUNCTION TABLE (each gate)

	INP	UTS		OUTPUT
Α	В	С	D	Υ
Н	Н	Н	Н	L
L	X	X	X	Н
Χ	L	Χ	X	Н
Χ	Χ	L	X	Н
Χ	Χ	Χ	L	Н

## logic diagram (positive logic)





Pin numbers shown are for the D, DB, DGV, J, NS, PW, and W packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)		
Output voltage range applied in high or low state	e, V <sub>O</sub> (see Notes 1 and 2)	$\dots$ -0.5 V to V <sub>CC</sub> + 0.5 V
Output voltage range applied in power-off state,	, VO (see Note 1)	0.5 V to 7 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)		–20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)		–50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )		±25 mA
Continuous current through V <sub>CC</sub> or GND		±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3):	D package	86°C/W
•••	DB package	96°C/W
	DGV package	127°C/W
	NS package	76°C/W
	PW package	113°C/W
Storage temperature range, T <sub>stq</sub>		–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions (see Note 4)

			SN54L\	/20A	SN74L	V20A	UNIT	
			MIN	MAX	MIN	MAX	UNII	
Vcc	Supply voltage		2	5.5	2	5.5	V	
		V <sub>CC</sub> = 2 V	1.5		1.5			
V	High level innet calls as	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V <sub>CC</sub> × 0.7		$V_{CC} \times 0.7$		V	
VIH	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		l v	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$			
		V <sub>CC</sub> = 2 V		0.5		0.5		
V.	Low level input valtage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V	$CC \times 0.3$	V	CC×0.3	V	
V <sub>IL</sub>	Low-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$	V	$CC \times 0.3$	V	CC×0.3	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		C × 0.3	V	CC×0.3		
٧ı	Input voltage		0,0	5.5	0	5.5	V	
VO	Output voltage		0	VCC	0	VCC	V	
		V <sub>CC</sub> = 2 V	S. S	-50		-50	μΑ	
	High lovel cutout current	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2		-2		
ЮН	High-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		-6		-6	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12		-12		
		$V_{CC} = 2 V$		50		50	μΑ	
	Low lovel output ourrent	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		2		
lOL	Low-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		6		6	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12		12	1	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200		200		
Δt/Δv	Input transition rise or fall rate	$V_{CC} = 3 V \text{ to } 3.6 V$		100		100	ns/V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20		20		
TA	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			SN54LV20A	SN74LV20A	LINIT
PARAMETER	TEST CONDITIONS	VCC	MIN TYP MAX	MIN TYP MAX	UNIT
	I <sub>OH</sub> = -50 μA	2 V to 5.5 V	V <sub>CC</sub> -0.1	V <sub>CC</sub> -0.1	
.,	$I_{OH} = -2 \text{ mA}$	2.3 V	2	2	V
VOH	$I_{OH} = -6 \text{ mA}$	3 V	2.48	2.48	V
	I <sub>OH</sub> = -12 mA	4.5 V	3.8	3.8	
	I <sub>OL</sub> = 50 μA	2 V to 5.5 V	0.1	0.1	
V	I <sub>OL</sub> = 2 mA	2.3 V	0.4	0.4	V
VOL	I <sub>OL</sub> = 6 mA	3 V	0.44	0.44	V
	I <sub>OL</sub> = 12 mA	4.5 V	0.55	0.55	
lį	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V	±1	±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V	20	20	μΑ
l <sub>off</sub>	$V_I$ or $V_O = 0$ to 5.5 $V$	0	5	5	μΑ
Ci	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	1.9	1.9	pF

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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 2.5 V $\pm$ 0.2 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T <sub>A</sub> = 25°C		SN54LV20A	SN74LV20A		UNIT	
PARAMETER	(INPUT)	(OUTPUT) CAPACITANCE		MIN	TYP	MAX	MIN MAX	MIN	MAX	UNII
t <sub>pd</sub>	A, B, C, or D	Υ	C <sub>L</sub> = 15 pF		6.8*	11.6*	1* 13.5*	1	13.5	ns
<sup>t</sup> pd	A, B, C, or D	Υ	C <sub>L</sub> = 50 pF		9.2	15.3	1 18.5	1	18.5	ns

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	METER FROM TO (OUTPUT)		LOAD	T <sub>A</sub> = 25°C		SN54LV20A	SN74LV20A		LINIT	
PARAMETER			CAPACITANCE	MIN	TYP	MAX	MIN MAX	MIN	MAX	UNIT
t <sub>pd</sub>	A, B, C, or D	Υ	C <sub>L</sub> = 15 pF		4.9*	6.6*	13 8*	1	8	ns
t <sub>pd</sub>	A, B, C, or D	Υ	C <sub>L</sub> = 50 pF		6.5	10.1	11.5	1	11.5	ns

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T <sub>A</sub> = 25°C		SN54LV20A	SN74LV20A		UNIT	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN MAX	MIN	MAX	UNII
t <sub>pd</sub>	A, B, C, or D	Υ	C <sub>L</sub> = 15 pF		3.7*	5*	13 6*	1	6	ns
t <sub>pd</sub>	A, B, C, or D	Υ	C <sub>L</sub> = 50 pF		4.8	7	1 8	1	8	ns

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.

## noise characteristics, $V_{CC} = 3.3 \text{ V}$ , $C_L = 50 \text{ pF}$ , $T_A = 25^{\circ}\text{C}$ (see Note 5)

	DADAMETED	SN			
	PARAMETER	MIN	TYP	MAX	UNIT
VOL(P)	Quiet output, maximum dynamic VOL		0.2	0.8	V
VOL(V)	Quiet output, minimum dynamic V <sub>OL</sub>		0	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		3.2		V
VIH(D)	High-level dynamic input voltage	2.31			V
V <sub>IL(D)</sub>	Low-level dynamic input voltage			0.99	V

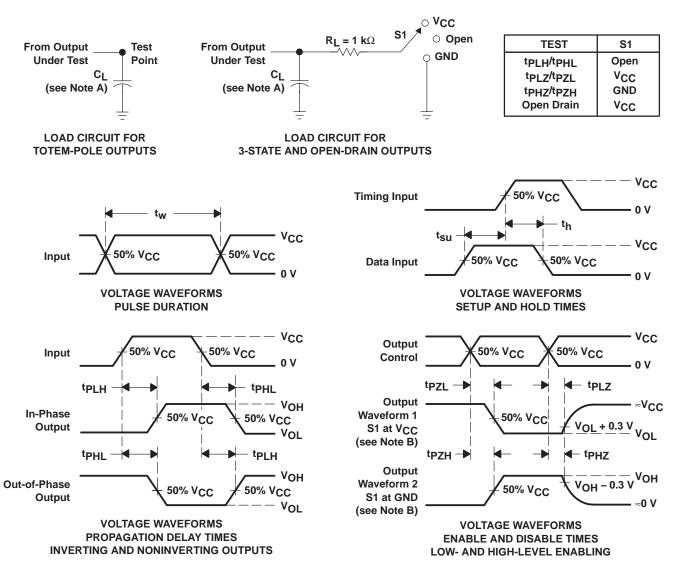
NOTE 5: Characteristics are for surface-mount packages only.

## operating characteristics, T<sub>A</sub> = 25°C

	PARAMETER			TEST CONDITIONS			UNIT
ſ	<u> </u>	Down discination consistence	C. F0 pF	f 40 MH-	3.3 V	20.5	pF
l	Cpd	Power dissipation capacitance	$C_L = 50 \text{ pF},$	f = 10 MHz	5 V	23.9	pΕ



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq 3$  ns,  $t_f \leq 3$  ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzi and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



#### PACKAGE OPTION ADDENDUM



i.com 30-May-2005

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LV20AD	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LV20ADBR	ACTIVE	SSOP	DB	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LV20ADBRE4	ACTIVE	SSOP	DB	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LV20ADGVR	ACTIVE	TVSOP	DGV	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV20ADGVRE4	ACTIVE	TVSOP	DGV	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV20ADR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LV20ADRE4	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LV20ANSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LV20ANSRE4	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LV20APW	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV20APWE4	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV20APWR	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV20APWRE4	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV20APWT	ACTIVE	TSSOP	PW	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV20APWTE4	ACTIVE	TSSOP	PW	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# **PACKAGE OPTION ADDENDUM**

30-May-2005

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## DGV (R-PDSO-G\*\*)

#### **24 PINS SHOWN**

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

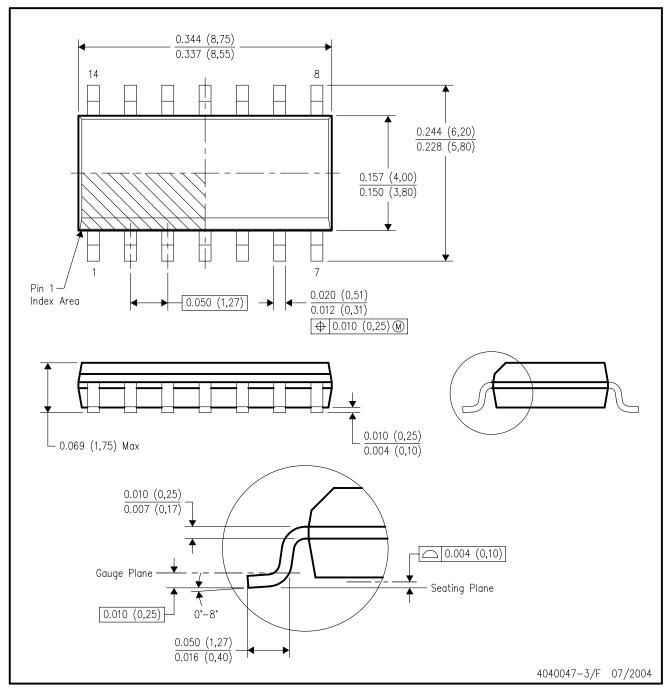
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



# D (R-PDSO-G14)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



## **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

## PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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